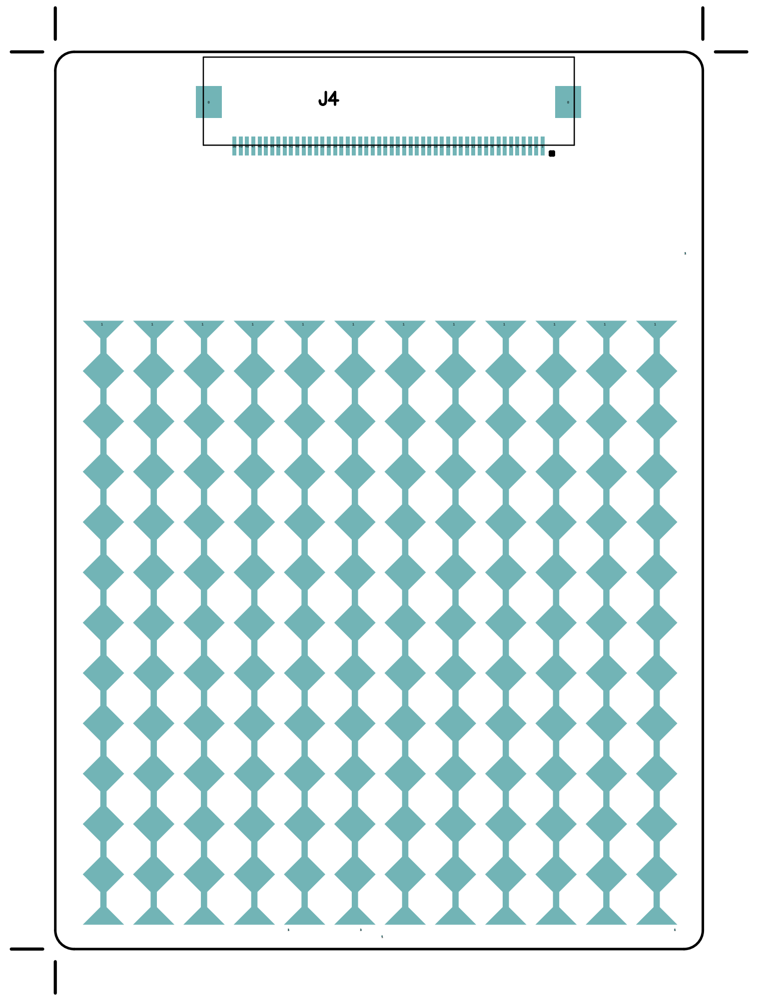
REV	ECO	Comments	Date
1	N/A	First Issue	17th May 2018
2	N/A	Tracking re-organised	10th Aug 2018
3	N/A	Change to Dev Tools part numbers	7th April 2020

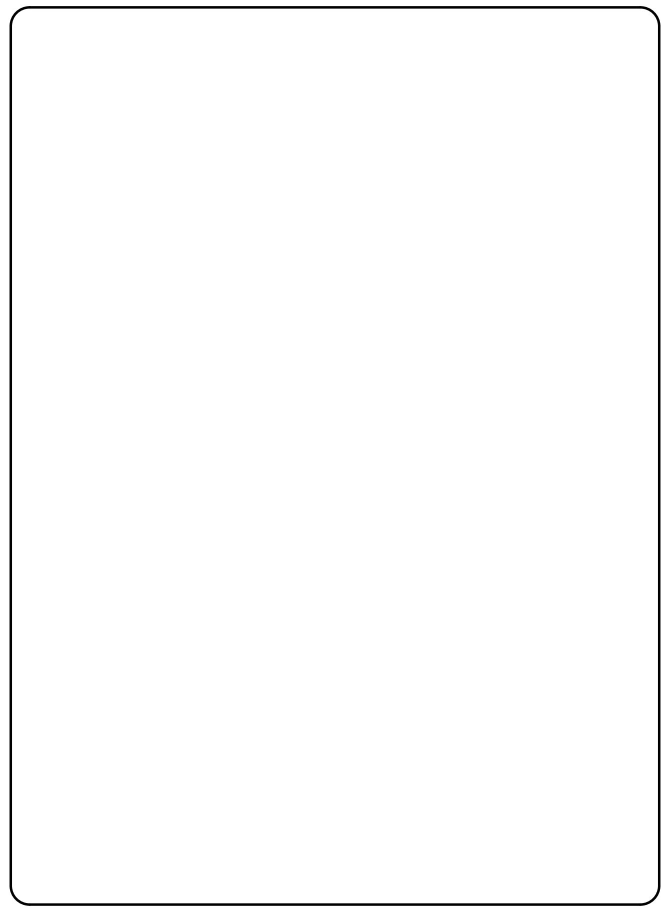


ASSEMBLY NOTES:

1. ALL COMPONENTS SHALL BE RoHS COMPLIANT.
2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
3. ALL TEST POINT THROUGH HOLES (DENOTED TPxx) SHALL BE FREE OF SOLDER.
4. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
5. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
6. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM HEIGHT OF 2mm.
7. PLACE LABELS ON THE LOCATION INDICATED.

MICROCHIP
Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: mXT144UD Touchpad
PART NUMBER: 00053
ASSEMBLY VARIANT: [No Variations]
PCB DESIGNER: Patrick Cassidy
GERBER FILE: Top Assembly Drawing
ENGINEER: Patrick Cassidy
BOARD NUMBER: 04–11168
DOCUMENT NUMBER: 02–00053–D
DATE: 09/04/2020
PCB FILE NAME: 11168.PcbDoc
LAYER NAME: Top Assembly (M11)
REV: 3
10mm
400mil



MICROCHIP

Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: mXT144UD Touchpad

PART NUMBER: 00053

ASSEMBLY VARIANT: [No Variations]

PCB DESIGNER: Patrick Cassidy

GERBER FILE: Bottom Assembly Drawing

ENGINEER: Patrick Cassidy

BOARD NUMBER: 04-11168

DOCUMENT NUMBER: 02-00053 -D

DATE: 09/04/2020

PCB FILE NAME: 11168.PcbDoc

LAYER NAME: Bottom Assembly (M10)

REV: 3

10mm
400mil


J4
04-11168-R3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